

# HOSTAFORM® S 9243 XAP®2 ECO-B

Impact modified, low emission

POM copolymer, modified Injection molding type, elastomer-containing; with higher impact strength and slightly lower hardness, rigidity and chemical resistance than the basic type HOSTAFORM® C 9021 Reduced emission grade, Emission according to VDA 275 < 5 mg/kg good weld strength. Burning rate according to FMVSS 302 < 100 mm/min (1 mm thickness) Preliminary Datasheet

ECO-B: Hostaform ECO-B is a POM-Copolymer with the same properties and performance as standard grades but produced with sustainability in mind. Using a mass-balance approach, biogenic feedstocks are used to offset the use of fossil-based raw materials and decrease greenhouse gas emissions. The process is audited and certified according to the ISCC Plus mass balance approach.

## Rheological properties

Melt volume-flow rate	4 cm <sup>3</sup> /10min	ISO 1133
Temperature	190 °C	
Load	2.16 kg	
Moulding shrinkage range, parallel	1.9 %	ISO 294-4, 2577
Moulding shrinkage range, normal	1.8 %	ISO 294-4, 2577

## Typical mechanical properties

Tensile Modulus	1950 MPa	ISO 527-1/-2
Yield stress, 50mm/min	44 MPa	ISO 527-1/-2
Yield strain, 50mm/min	9 %	ISO 527-1/-2
Nominal strain at break	40 %	ISO 527-1/-2
Flexural Modulus	1850 MPa	ISO 178
Tensile creep modulus, 1h	1700 MPa	ISO 899-1
Tensile creep modulus, 1000h	950 MPa	ISO 899-1
Charpy impact strength, 23°C	NB kJ/m <sup>2</sup>	ISO 179/1eU
Charpy impact strength, -30°C	200 <sup>[P]</sup> kJ/m <sup>2</sup>	ISO 179/1eU
Charpy notched impact strength, 23°C	15 kJ/m <sup>2</sup>	ISO 179/1eA
Charpy notched impact strength, -30°C	9 kJ/m <sup>2</sup>	ISO 179/1eA

[P]: Partial Break

## Thermal properties

Melting temperature, 10°C/min	166 °C	ISO 11357-1/-3
Temp. of deflection under load, 1.8 MPa	75 °C	ISO 75-1/-2
Vicat softening temperature, 50°C/h, 50N	130 °C	ISO 306
Coeff. of linear therm. expansion, parallel	120 E-6/K	ISO 11359-1/-2

## Electrical properties

Relative permittivity, 100Hz	3.8	IEC 62631-2-1
Relative permittivity, 1MHz	3.8	IEC 62631-2-1
Dissipation factor, 100Hz	30 E-4	IEC 62631-2-1
Dissipation factor, 1MHz	60 E-4	IEC 62631-2-1
Volume resistivity	1E11 Ohm.m	IEC 62631-3-1

# HOSTAFORM® S 9243 XAP®2 ECO-B

Surface resistivity	1E13 Ohm	IEC 62631-3-2
Comparative tracking index	PLC 0 PLC	UL 746A

## Other properties

Humidity absorption, 2mm	0.2 %	Sim. to ISO 62
Water absorption, 2mm	1 %	Sim. to ISO 62
Density	1330 kg/m <sup>3</sup>	ISO 1183

## Injection

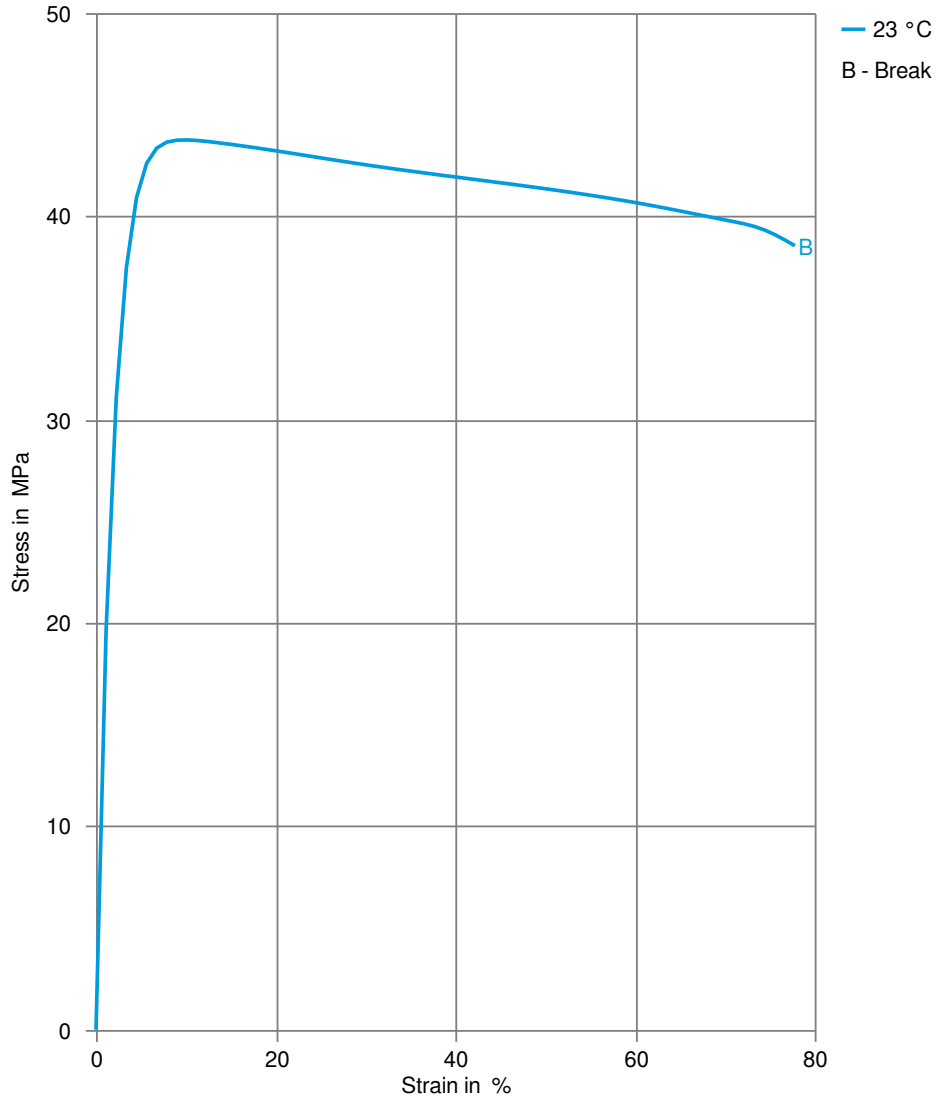
Drying Temperature	100 - 120 °C
Drying Time, Dehumidified Dryer	3 - 4 h
Processing Moisture Content	0.15 %
Screw tangential speed	0.2 - 0.21 m/s
Max. mould temperature	60 - 80 °C
Back pressure	2 MPa
Injection speed	slow-medium

## Characteristics

Additives	Release agent, Biobased
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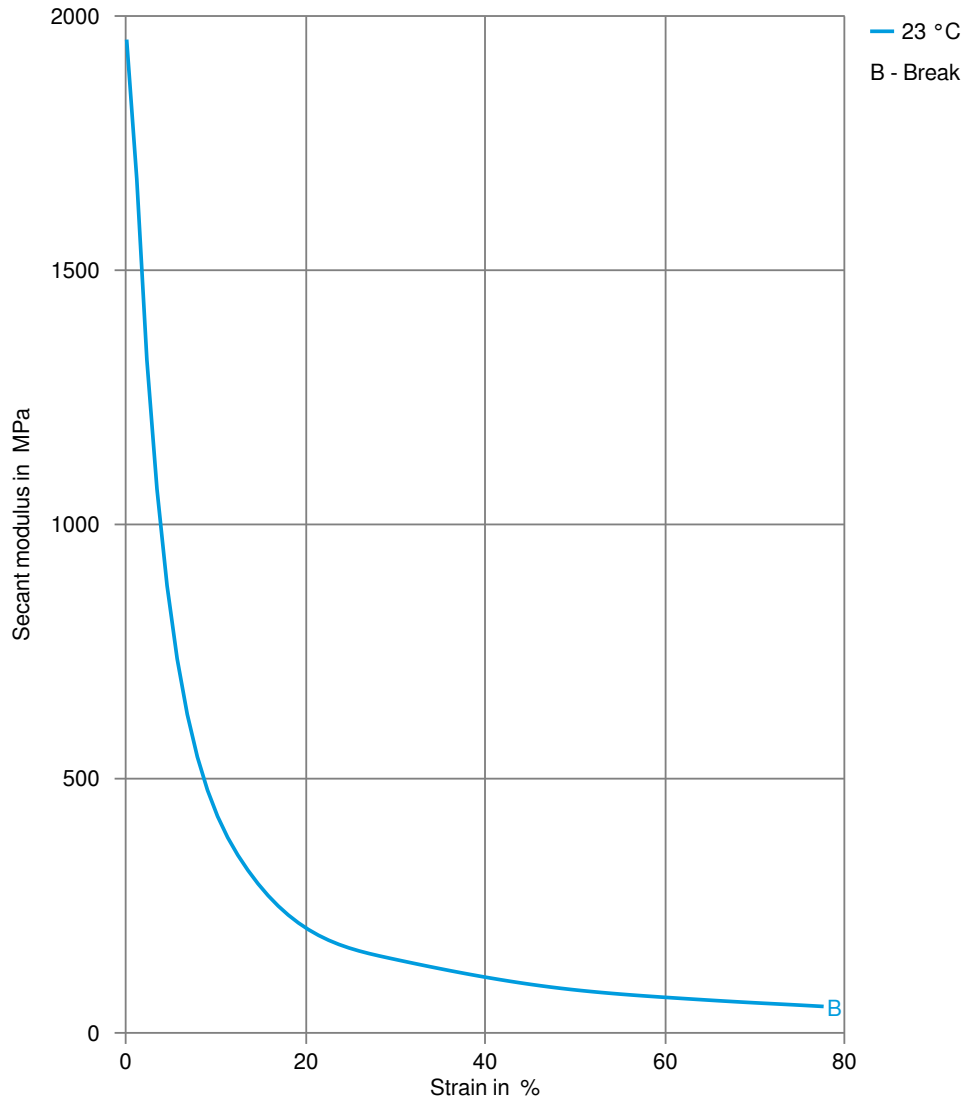
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## Stress-strain



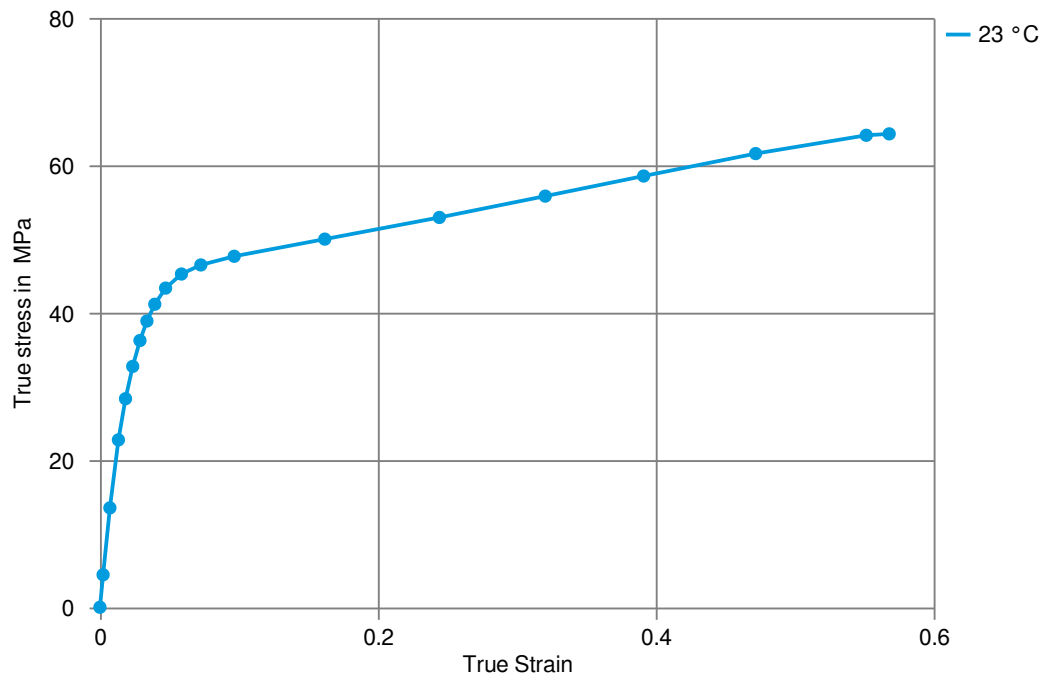
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## Secant modulus-strain



# HOSTAFORM® S 9243 XAP®2 ECO-B

## True stress-strain



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## Processing Texts

Pre-drying

It is normally not necessary to dry HOSTAFORM. However, should there be surface moisture (condensate) on the molding compound as a result of incorrect storage, drying is required. A circulating air drying cabinet can be used for this purpose if the granul

Longer pre-drying times/storage

The product can then be stored in standard conditions until processed.

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